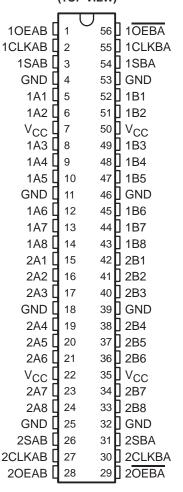
- Members of the Texas Instruments
 Widebus ™ Family
- Independent Registers and Enables for A and B Buses
- Multiplexed Real-Time and Stored Data
- Flow-Through Architecture Optimizes
 PCB Layout
- Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise
- EPIC ™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

The 'AC16652 are 16-bit bus transceivers that consist of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. They can be used as two 8-bit transceivers or one 16-bit transceiver.

Complementary output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'AC16652.

54AC16652... WD PACKAGE 74AC16652... DL PACKAGE (TOP VIEW)





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54AC16652, 74AC16652 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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description (continued)

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

The 74AC16652 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16652 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16652 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

		INPU	гѕ			DATA	A 1/0†	ODED ATION OF FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	L	L	Х	Х	Input	Input	Isolation
L	Н	\uparrow	1	Χ	X	Input	Input	Store A and B data
Х	Н	\uparrow	L	Х	Х	Input	Unspecified [‡]	Store A, hold B
Н	Н	\uparrow	1	X [‡]	X	Input	Output	Store A in both registers
L	Х	L	1	Х	Х	Unspecified [‡]	Input	Hold A, store B
L	L	\uparrow	\uparrow	X	X‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	L	Χ	Н	X	Input	Output	Stored A data to B bus
Н	L	L	L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

[†] The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.

Select control = H; clocks must be staggered in order to load both registers.



[‡] Select control = L; clocks can occur simultaneously.

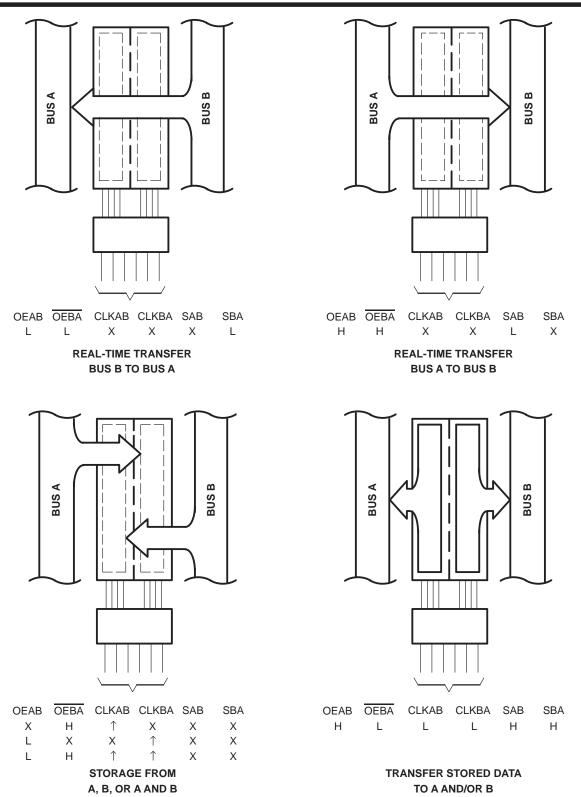
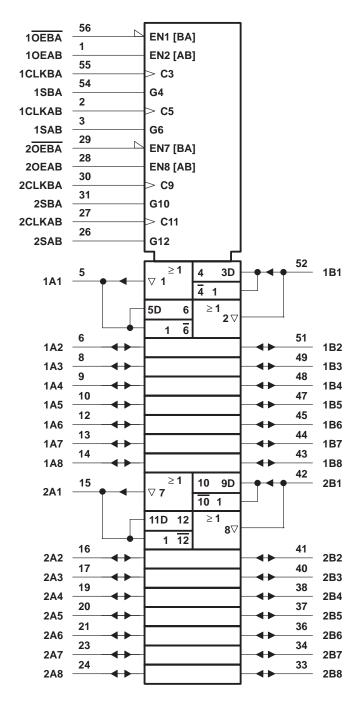


Figure 1. Bus-Management Functions



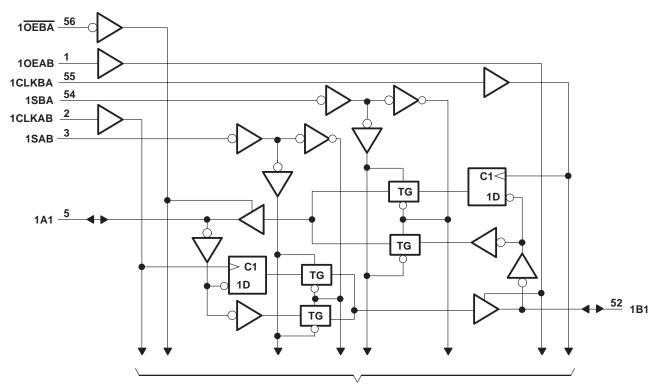
logic symbol†



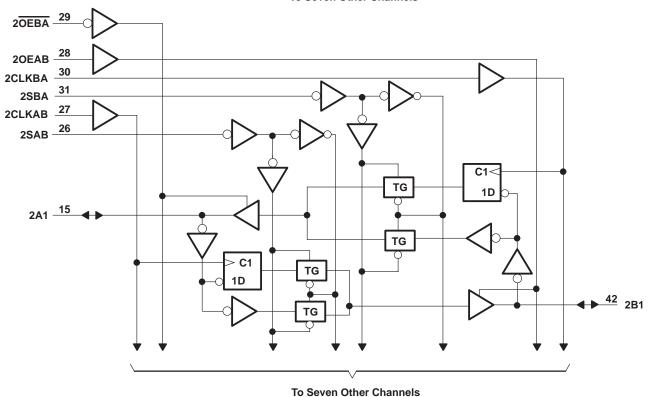
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To Seven Other Channels





54AC16652, 74AC16652 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)–0	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Note 1)0	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum package power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			54	AC1665	2	74	AC1665	2	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage (see Note 4)		3	5	5.5	3	5	5.5	V
		V _{CC} = 3 V	2.1			2.1			
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		V _{CC} = 5.5 V	3.85			3.85			
		V _{CC} = 3 V			0.9			0.9	
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$		S.	1.35			1.35	V
		V _{CC} = 5.5 V		Q	1.65			1.65	
VI	Input voltage		0	6	VCC	0		VCC	V
VO	Output voltage		0 4	3	VCC	0		VCC	V
		V _{CC} = 3 V	200		-4			-4	
ЮН	High-level output current	V _{CC} = 4.5 V	4		-24			-24	mA
		V _{CC} = 5.5 V			-24			-24	
		VCC = 3 V			12			12	
lOL	Low-level output current	V _{CC} = 4.5 V			24			24	mA
		V _{CC} = 5.5 V			24			24	
Δt/Δν	Input transition rise or fall rate		0		10	0		10	ns/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTES: 3. Unused inputs must be held high or low to prevent them from floating.

4. All V_{CC} and GND pins must be connected to the proper voltage power supply.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	DAMETED	TEST CONDITIONS	V	T,	_A = 25°C	54AC16652	74AC16652	UNIT
PAI	RAMETER	TEST CONDITIONS	VCC	MIN	TYP MAX	MIN MAX	MIN MAX	UNII
			3 V	2.9		2.9	2.9	
		I _{OH} = -50 μA	4.5 V	4.4		4.4	4.4	
			5.5 V	5.4		5.4	5.4	
Vari		I _{OH} = -4 mA	3 V	2.58		2.4	2.48	V
VOH		Jan - 24 mA	4.5 V	3.94		3.7	3.8	V
		$I_{OH} = -24 \text{ mA}$	5.5 V	4.94		4.7	4.8	
		I _{OH} = -50 mA [†]	5.5 V			3.85		
		I _{OH} = -75 mA [†]	5.5 V			1	3.85	1
			3 V		0.1	0.1	0.1	
		I _{OL} = 50 μA	4.5 V		0.1	0.1	0.1	
			5.5 V		0.1	3 0.1	0.1	
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		I _{OL} = 12 mA	3 V		0.36	0.5	0.44	V
VOL		J	4.5 V		0.36	0.5	0.44	V
		I _{OL} = 24 mA	5.5 V		0.36	0.5	0.44	1
		I _{OL} = 50 mA [†]	5.5 V			1.65		1
		I _{OL} = 75 mA [†]	5.5 V				1.65	1
I _I	Control inputs	V _I = V _{CC} or GND	5.5 V		±0.1	±1	±1	μΑ
loz	A or B ports‡	V _O = V _{CC} or GND	5.5 V		±0.5	±10	±5	μΑ
Icc	-	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		8	160	80	μΑ
Ci	Control inputs	V _I = V _{CC} or GND	5 V		4			pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12			pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

		T _A = 2	25°C	54AC1	6652	74AC1	6652	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency	0	55	0	55	0	55	MHz
t _W	Pulse duration, CLKAB or CLKBA high or low	9		9	1/2	9		ns
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	7		7		7		ns
th	Hold time, A after CLKAB↑ or B after CLKBA↑	0		0		0		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 2)

		T _A = 2	25°C	54AC1	6652	74AC1	6652	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency	0	95	0	95	0	95	MHz
t _W	Pulse duration, CLKAB or CLKBA high or low	5		5	140	5		ns
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5		4.5		4.5		ns
t _h	Hold time, A after CLKAB↑ or B after CLKBA↑	0		0		0		ns



 $[\]mbox{\ensuremath{\mbox{\footnote{1}}}}\mbox{\ensuremath{\mbox{\footnote{1}}}}\mbox{\footnote{1}}\mbox{\fo$

54AC16652, 74AC16652 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	T,	4 = 25°C	;	54AC1	6652	74AC1	6652	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f _{max}			55			55		55		MHz
^t PLH	A or B	B or A	3.6	10.4	13.7	3.6	17.1	3.6	15.6	ns
^t PHL	AOIB	BOIA	4.1	10.9	14.3	4.1	16.3	4.1	15.4	115
t _{PLH}	CLKBA or CLKAB	A or B	5.1	13.6	17.3	5.1	21.2	5.1	19.5	ns
t _{PHL}	CERBA OF CERAB	AOIB	5.4	13.5	17.2	5.4	19.9	5.4	18.8	115
t _{PLH}	SBA or SAB	A or B	5.8	15.0	18.7	5.8	23.3	5.8	21.4	ns
^t PHL	(with A or B high)	AUIB	5.4	13.1	16.7	5.4	19.1	5.4	18.1	115
t _{PLH}	SBA or SAB	A or B	4.2	11.8	15.2	4.2 4	18.9	4.2	17.4	ns
t _{PHL}	(with A or B low)	AOIB	5.9	14.4	18.3	5.9	21.7	5.9	20.3	115
^t PZH	OEBA	А	4.2	11.8	15.1	4,2	18.8	4.2	17.2	ns
t _{PZL}	OEBA	A	6	16.2	20.6	6	25.3	6	23.5	115
^t PHZ	OEBA	А	4.6	8.1	10	4.6	10.9	4.6	10.6	ns
t _{PLZ}	OEBA	A	4.4	7.6	9.6	4.4	10.6	4.4	10.3	115
^t PZH	OFAR	В	4.1	11.5	14.6	4.1	18.1	4.1	16.6	ns
t _{PZL}	OEAB	٥	6	16.0	20	6	24.6	6	22.7	115
^t PHZ	OFAR	В	4.3	7.2	9	4.3	9.7	4.3	9.5	ns
tPLZ	OEAB	, b	3.9	6.7	8.6	3.9	9.2	3.9	9.1	115

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 2)

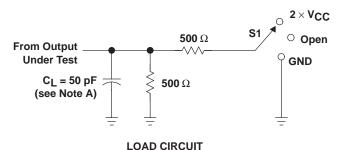
PARAMETER	FROM	то	Т,	Δ = 25°C	;	54AC1	6652	74AC1	6652	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
f _{max}			95			95		95		MHz
t _{PLH}	A or B	B or A	2.7	6.1	8.8	2.7	10.7	2.7	9.9	ns
^t PHL	AOIB	BOIA	3	6.3	9.2	3	10.8	3	10.2	115
^t PLH	CLKBA or CLKAB	A or B	3.9	7.8	10.9	3.9	13.3	3.9	12.2	ns
^t PHL	CERBA OF CERAB	AOIB	4.2	7.8	11.1	4.2	13.2	4.2	12.3	115
^t PLH	SBA or SAB	A or B	4.5	8.8	12.1	4.5	15	4.5	13.8	ns
^t PHL	(with A or B high)	AOIB	4.1	7.7	11	4.1	12.9	4.1	12.1	115
^t PLH	SBA or SAB	A or B	3.1	6.7	9.7	3.1	11.9	3.1	11	ns
^t PHL	(with A or B low)	AOIB	4.6	8.8	12.2	4.6	14.9	4.6	13.8	115
^t PZH	OEBA	А	3.1	6.7	9.5	3.1	11.6	3.1	10.7	ns
^t PZL	OEBA	A	4.5	8.3	11.8	4.5	14.4	4.5	13.2	115
^t PHZ	OEBA	А	4.6	6.5	8.3	4.6	9	4.6	8.8	ns
t _{PLZ}	OEBA	٨	4.1	6.1	8.1	4.1	9.1	4.1	8.7	115
^t PZH	OFAR	В	3.1	6.6	9.3	3.1	11.3	3.1	10.5	ns
t _{PZL}	OEAB		4.6	8.2	11.6	4.6	14.1	4.6	13	115
^t PHZ	OFAR	В	4.2	5.9	7.7	4.2	8.3	4.2	8	ns
^t PLZ	OEAB	В	3.7	5.5	7.4	3.7	8.3	3.7	7.8	115

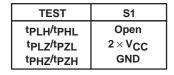


operating characteristics, V_{CC} = 5 V, T_A = 25°C

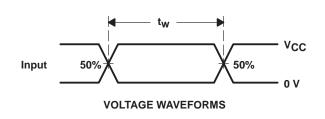
	PARAMETER		TEST CO	TYP	UNIT	
C .	Downs discipation conscitance per transcriver	Outputs enabled	$C_1 = 50 pF$	f = 1 MHz	57	nE
Cpd	Power dissipation capacitance per transceiver	Outputs disabled	CL = 50 pr,	I = I IVITZ	13	pF

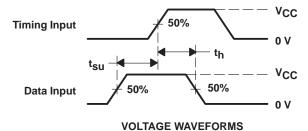
PARAMETER MEASUREMENT INFORMATION

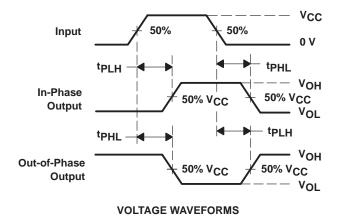


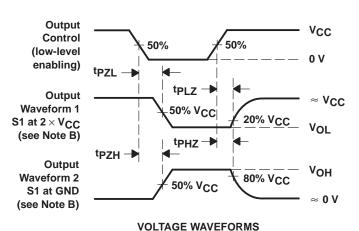












NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_\Gamma = 3$ ns, $t_f = 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms







.com 6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC16652DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16652DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16652DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16652DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC16652DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AC16652DLR	SSOP	DL	56	1000	346.0	346.0	49.0

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